

January 7, 1998

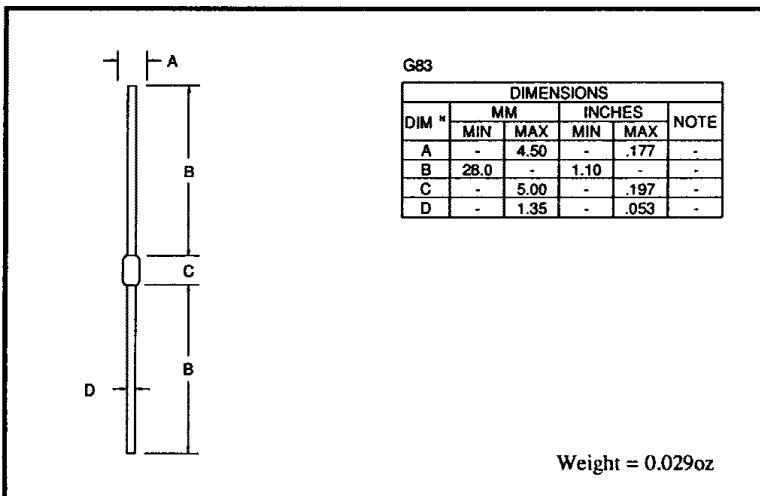
**AXIAL LEADED HERMETICALLY SEALED
SUPERFAST RECTIFIER DIODE**
**QUICK
REFERENCE DATA**

- Very low reverse recovery time
- Low forward voltage drop
- Glass passivated for hermetic sealing
- Low switching losses
- Soft, non-snap off, recovery characteristics

- $V_R = 50 - 200V$
- $I_F = 4.0A$
- $t_{rr} = 30\text{ns}$
- $V_F = 1.05V$

ABSOLUTE MAXIMUM RATINGS (@ 25°C unless otherwise specified)

	Symbol	3PFT05	3PFT1	3PFT15	3PFT2	Unit
Working reverse voltage	V_{RWM}	50	100	150	200	V
Repetitive reverse voltage	V_{RRM}	50	100	150	200	V
Average forward current (@ 55°C, lead length 0.375")	$I_{F(AV)}$	← → 4.0				A
Repetitive surge current (@ 55°C in free air, lead length 0.375")	I_{FRM}	← → 25				A
Non-repetitive surge current ($t_p = 8.3\text{mS}$, @ V_R & T_{jmax})	I_{FSM}	← → 90				A
Storage temperature range	T_{STG}	← → -65 to +175				°C
Operating temperature range	T_{OP}	← → -65 to +175				°C

MECHANICAL


These products are qualified in Europe to DEF STAN 59-61 (PART 80)/029 available to F and FX levels.

one source. one solution.[®]

RECTIFIER, up to 200V, 4A, 30ns

3PFT05

3PFT1

3PFT15

3PFT2

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ELECTRICAL CHARACTERISTICS (@ 25°C unless otherwise specified)

	Symbol	3PFT05	3PFT1	3PFT15	3PFT2	Unit
Average forward current max. (pcb mounted; T _A = 55°C) for sine wave for square wave (d = 0.5)	I _{F(AV)}	1.8				A
	I _{F(AV)}	1.9				A
Average forward current max. (T _L = 55°C; L = 3/8") for sine wave for square wave	I _{F(AV)}	3.8				A
	I _{F(AV)}	4.0				A
I ² t for fusing (t = 8.3mS) max.	I ² t	33				A ² S
Forward voltage drop max. @ I _F = 3.5A, T _j = 25°C	V _F	1.05				V
Reverse current max. @ V _{RWM} , T _j = 25°C @ V _{RWM} , T _j = 100°C	I _R	1.0				µA
	I _R	10				µA
Reverse recovery time max. 0.5A I _F to 1.0A I _R . Recovers to 0.25A I _{RR} .	t _{rr}	30				nS
Junction capacitance typ. @ V _R = 5V , f = 1MHz	C _j	92				pF

THERMAL CHARACTERISTICS

	Symbol	3PFT05	3PFT1	3PFT15	3PFT2	Unit
Thermal resistance - junction to lead Lead length = 0.375" Lead length = 0.0"	R _{θJL}	26				°C/W
	R _{θJL}	12				°C/W
Thermal resistance - junction to amb. on 0.06" thick pcb. 1 oz. copper.	R _{θJA}	75				°C/W

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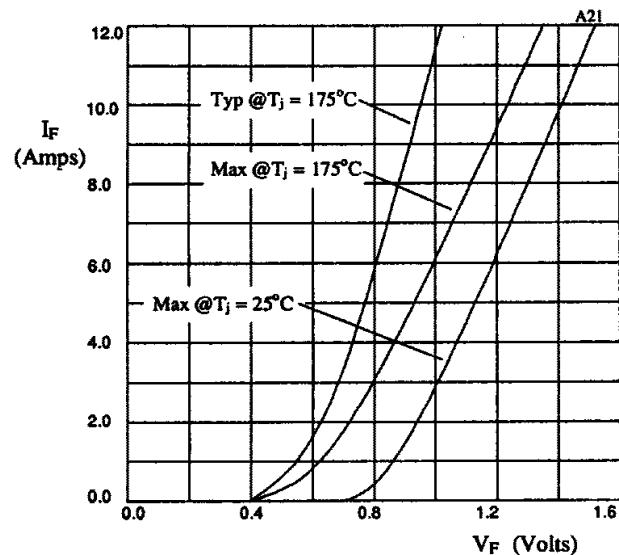


Fig 1. Forward voltage drops as a function of forward current.

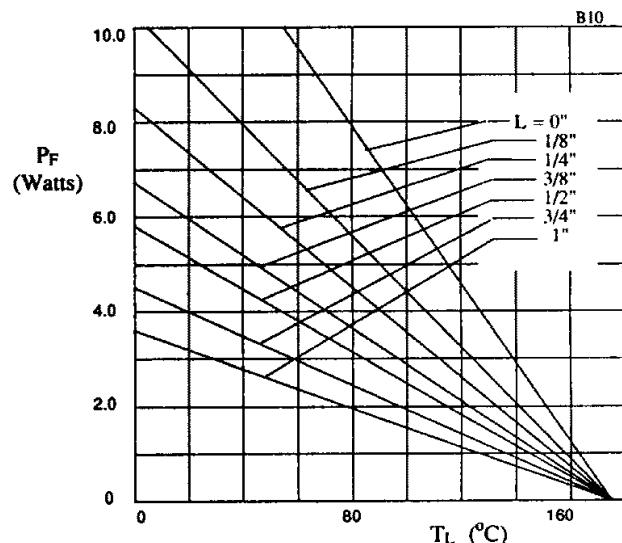


Fig 2. Maximum power versus lead temperature.

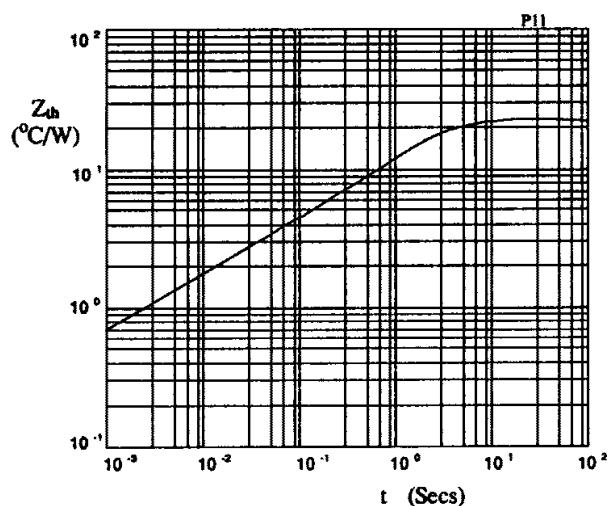


Fig 3. Transient thermal impedance characteristic.

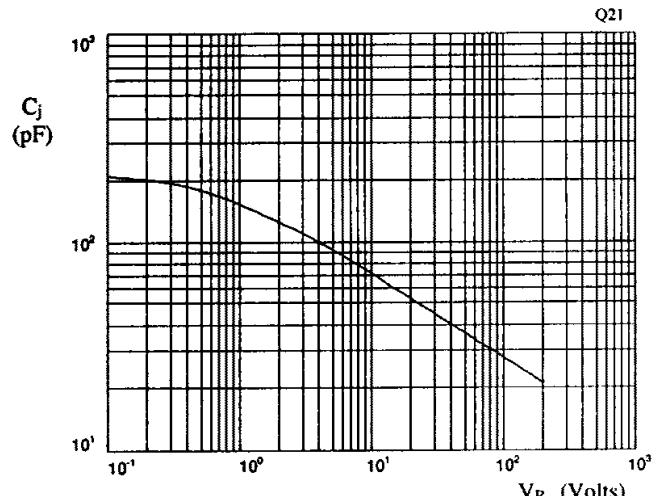


Fig 4. Typical junction capacitance as a function of reverse voltage.

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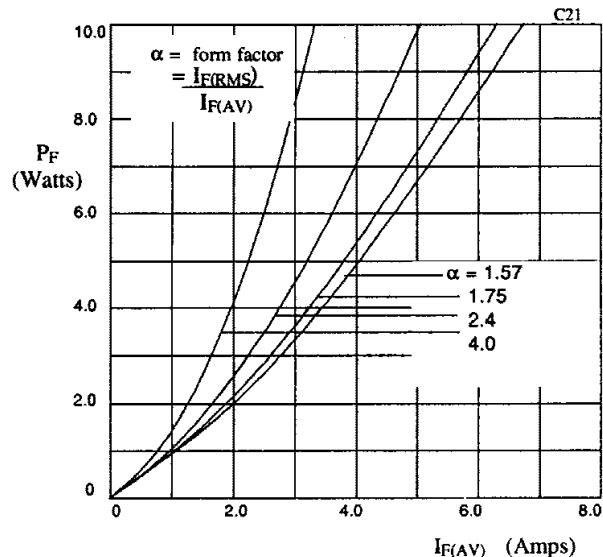


Fig 5. Forward power dissipation as a function of forward current, for sinusoidal operation.

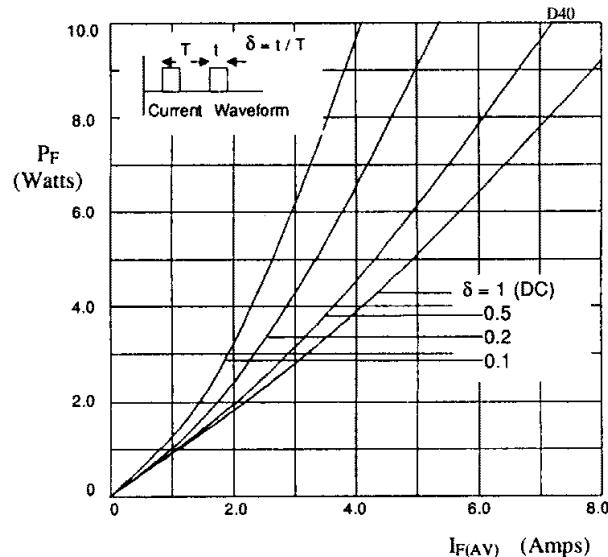


Fig 6. Forward power dissipation as a function of forward current, for square wave operation.

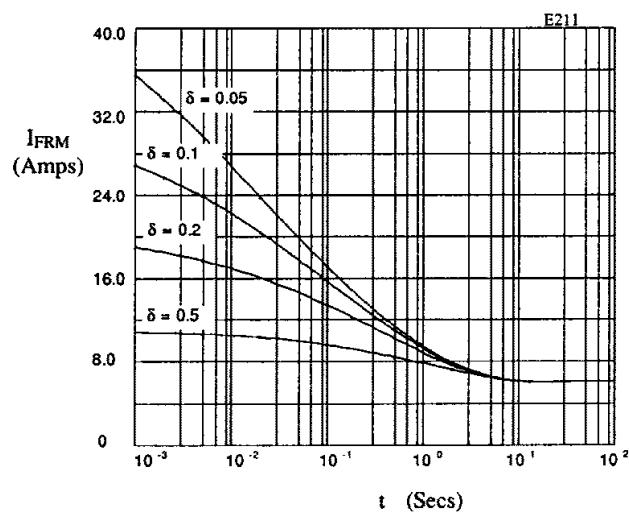


Fig 7. Typical repetitive forward current as a function of pulse width at 55°C; $R_{\theta JL} = 22 \text{ }^\circ\text{C/W}$; V_{RWM} during $1 - \delta$.

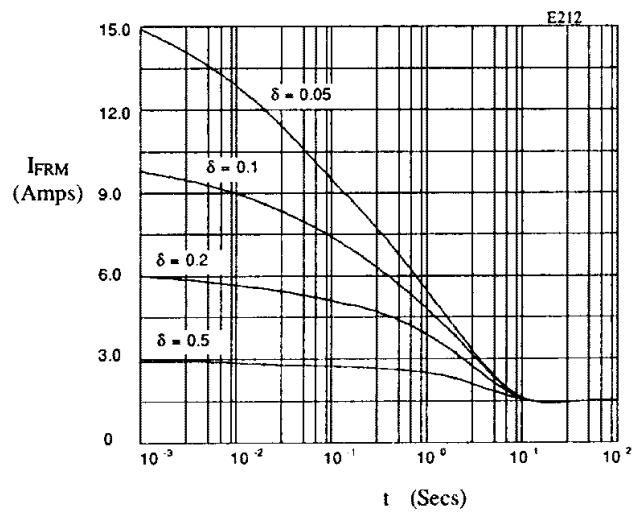


Fig 8. Typical repetitive forward current as a function of pulse width at 100°C; $R_{\theta JL} = 75 \text{ }^\circ\text{C/W}$; V_{RWM} during $1 - \delta$.